



Epoxy for BGA、CSP Under-fill

Product Description

JD642-6 is one component epoxy adhesive for electronic devices bonding. This product is easy to operate and suited for various applications of electronic components, such as casting and sealing. This resin can be fast cured at high temperature, is able to reduce the working time and increase the efficiency at the same time. This product develops tough, strong, structural bonds which provide excellent shear, peel and impact strength. The durability of this resin is very high levels and this resin can pass many environmental test experiments.

Features

1. This product is solvent-free, non-volatile, system and has no volative materials and will not release any toxic volatilizations.
2. This resin is low viscosity, excellent fluidity and easy to operate. It is suited for casting.
3. The hardening surface will not exhibit a surface oiliness and poor gloss.
4. This product complies to the 2011/65/EU RoHS regulations.
5. This product complies to chlorine < 900ppm, bromine < 900ppm, chlorine + bromine < 1500ppm.

Typical Uncured Properties

Appearance	Liquid
Color	Black
Viscosity 25°C, S21 20rpm, cps	240~450

Typical Curing Properties

Pot Life 25°C, days	2
Through Cure Time 130°C, min	10
Through Cure Time 150°C, min	5-8

Direction of Use

1. The package of this resin which is refrigerated in -40°C ~ -5°C can be brought to ambient conditions by allowing to stand at room temperature for 2 hours. Do not loosen container cover before temperature equilibration.
2. It should be applied to a clean surface which is free of dirt, grease or mold release. In many cases, a simple solvent wipe is sufficient.
3. After heat curing stage, cool down the part gradually can minimize the thermal stress.
4. Cure time on the really part will depend upon factors such as part geometry, materials to be bonded, bondline thickness and efficiency of the oven. Cure schedule should be confirmed with actual production parts and equipment

Rework Process :

I - Component Removal

Before component removal, component solder joints must be heated above their reflow temperature in order to reduce the damage to the circuit board. When the temperature of the circuit board is about 260~280°C, the underfill will be soft and easy to remove. It may pull out the pads if the circuit board is heated too slowly or to an excessive temperature. After heating the circuit board, the component can be easily removed by twisting or a vacuum pick-up nozzle.

II - Site preparation

After component removal, there are two methods to clean the residues.

(I) Scraping

Heat the soldering iron up to 250~300°C and scrape off the underfill without any damage of pads on the circuit board. Alternatively, heat the bottom of substrate and scrape off the underfill with a metal squeegee.

(II) Rotating Brush

Apply pressure onto the brush to clean the residues. Too large pressure may wear out the brush or increase the board damage. The types of the circuit board or the solderball composition will influence the decision to apply solderpaste or flux.

III - Component Replacement

The user can use isopropanol or a flux pen to make sure that no residues remain on the circuit board after cleaning. Brush the solderpaste or flux on the board. After aligning the new package, it will be placed by vacuum, reflowed with hot air and underfill, followed by the underfill cure step.

Typical Cured Properties*1

Glass Transition Temp.,(TMA), °C	103
CTE*2 (<Tg), μm/m/°C	64
CTE*2 (>Tg), μm/m/°C	254
Specific Heat 0°C, J/g°C	1.11
Specific Heat 25°C, J/g°C	1.25
Specific Heat 50°C, J/g°C	1.64
Specific Heat 75°C, J/g°C	1.81
Specific Heat 100°C, J/g°C	1.91
Durometer Hardness, Shore D	80
Specific Gravity	1.19
Water Absorption Ratio (25°C /24hr), %	0.21
Water Absorption Ratio (80°C /24hr), %	3.52
Water Absorption Ratio (97°C /1.5hr), %	1.83
Volume Shrinkage, %	2.0
Flexural Modulus, GPa	2.7
Degradation Temp., (TGA 10°C /min), °C	264
Weight Loss Ratio@100°C, %	0.14
Weight Loss Ratio@150°C, %	0.56
Weight Loss Ratio@200°C, %	1.70
Weight Loss Ratio@250°C, %	3.74
Weight Loss Ratio@300°C, %	6.80
Weight Loss Ratio@350°C, %	14.61
Volume Resistivity, ohm-cm	4.5*10 ¹⁵
Surface Resistivity, ohm	4.5*10 ¹⁴

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

Dielectric Constant 1KHZ	3.40
Dielectric Constant 1GHZ	3.20
Dielectric Constant 2GHZ	3.23
Dielectric Loss 1GHZ	0.010
Dielectric Loss 2GHZ	0.009
Dielectric Strength, KV/mm	19
Working Temperature Range, °C	-40~120

*1 Specimen Cure Condition : 130°C / 20min

*2 CTE: Coefficient of Thermal Expansion

Storage and Shelf Life

This resin should be kept without any possibility of moisture and heat exposure. It should be storage at -40°C ~ -5°C before opening the containers. Shelf life of this product is six months. Before using, it should place this product at 14~34°C for 2 hours. The properties will be changed when replace this product at room temperature for long time.

Caution

Some findings indicate a lack of potential for carcinogenicity with the compositions of this product by long term recurrent application to the skin. However, contact with skin is likely to produce mild transient reddening. It is important to remove adhesive from skin with soap and water thoroughly. DO NOT use solvents for cleaning hands. This product of moderate acute toxicity by swallowing. If swallowed, call a physician. Avoid contact with eyes. In case of contact, flush with water for at least 15 minutes and get medical attention immediately. For specific information on this product, consult the Material Safety Data Sheet.

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